

**EVLYS LTD. - POWER SEMICONDUCTORS DEVICES -**  
**Wholesale and Retail.**

**Phase Control Disc Thyristor Type DT99-3200-44**

High power cycling capability / Low on-state and switching losses  
 Designed for traction and industrial applications

Mean on-state current	I <sub>TAV</sub>	3200 A			
Repetitive peak off-state voltage	V <sub>DRM</sub>	2900 ÷ 4400 V			
Repetitive peak reverse voltage	V <sub>RRM</sub>				
Turn-off time	t <sub>q</sub>	800 $\mu$ s			
V <sub>DRM</sub> , V <sub>RRM</sub> , V	3800	4000	4200	4400	
Voltage code	38	40	42	44	
T <sub>j</sub> , °C			– 60 ÷ 125		

**MAXIMUM ALLOWABLE RATINGS**

Symbols and parameters		Units	Values	Test conditions	
<b>ON-STATE</b>					
I <sub>TAV</sub>	Mean on-state current	A	3200 4325	T <sub>c</sub> = 91 °C, Double side cooled T <sub>c</sub> = 70 °C, Double side cooled 180° half-sine wave; 50 Hz	
I <sub>TRMS</sub>	RMS on-state current	A	5024	T <sub>c</sub> = 91 °C, Double side cooled 180° half-sine wave; 50 Hz	
I <sub>TSM</sub>	Surge on-state current	kA	60.0 69.0	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 50 Hz (t <sub>p</sub> =10 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 $\mu$ s; dI <sub>G</sub> /dt≥1 A/ $\mu$ s
			63.0 72.0	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 60 Hz (t <sub>p</sub> =8.3 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 $\mu$ s; dI <sub>G</sub> /dt≥1 A/ $\mu$ s
I <sup>2</sup> t	Safety factor	A <sup>2</sup> ·10 <sup>3</sup>	18000 23805	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 50 Hz (t <sub>p</sub> =10 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 $\mu$ s; dI <sub>G</sub> /dt≥1 A/ $\mu$ s
			16470 21510	T <sub>j</sub> =T <sub>j</sub> max T <sub>j</sub> =25 °C	180° half-sine wave; 60 Hz (t <sub>p</sub> =8.3 ms); single pulse; V <sub>D</sub> =V <sub>R</sub> =0 V; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 $\mu$ s; dI <sub>G</sub> /dt≥1 A/ $\mu$ s
<b>BLOCKING</b>					
V <sub>DRM</sub> , V <sub>RRM</sub>	Repetitive peak off-state and Repetitive peak reverse voltages	V	3800÷4400	T <sub>j min</sub> < T <sub>j</sub> <T <sub>j max</sub> ; 180° half-sine wave; 50 Hz; Gate open	
V <sub>DSM</sub> , V <sub>RSM</sub>	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3900÷4500	T <sub>j min</sub> < T <sub>j</sub> <T <sub>j max</sub> ; 180° half-sine wave; 50 Hz;single pulse; Gate open	
V <sub>D</sub> , V <sub>R</sub>	Direct off-state and Direct reverse voltages	V	0.75·V <sub>DRM</sub> 0.75·V <sub>RRM</sub>	T <sub>j</sub> =T <sub>j</sub> max; Gate open	

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<b>TRIGGERING</b>				
I <sub>FGM</sub>	Peak forward gate current	A	12	T <sub>j</sub> =T <sub>j</sub> max
V <sub>RGM</sub>	Peak reverse gate voltage	V	5	
P <sub>G</sub>	Gate power dissipation	W	5	T <sub>j</sub> =T <sub>j</sub> max for DC gate current
<b>SWITCHING</b>				
(dI <sub>T</sub> /dt) <sub>crit</sub>	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/μs	1000	T <sub>j</sub> =T <sub>j</sub> max; V <sub>D</sub> =0.67·V <sub>DRM</sub> ; I <sub>TM</sub> =2 I <sub>TAV</sub> ; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 μs; dI <sub>G</sub> /dt≥1 A/μs
<b>THERMAL</b>				
T <sub>stg</sub>	Storage temperature	°C	-60 ÷ 125	
T <sub>j</sub>	Operating junction temperature	°C	-60 ÷ 125	
<b>MECHANICAL</b>				
F	Mounting force	kN	70.0 ÷ 90.0	
a	Acceleration	m/s <sup>2</sup>	50 100	Device unclamped Device clamped

## **CHARACTERISTICS**

Symbols and parameters		Units	Values	Conditions	
<b>ON-STATE</b>					
V <sub>TM</sub>	Peak on-state voltage, max	V	1.80	T <sub>j</sub> =25 °C; I <sub>TM</sub> =6300 A	
V <sub>T(TO)</sub>	On-state threshold voltage, max	V	0.95	T <sub>j</sub> =T <sub>j</sub> max;	
r <sub>T</sub>	On-state slope resistance, max	mΩ	0.150	0.5 π I <sub>TAV</sub> < I <sub>T</sub> < 1.5 π I <sub>TAV</sub>	
I <sub>L</sub>	Latching current, max	mA	1500	T <sub>j</sub> =25 °C; V <sub>D</sub> =12 V; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 μs; dI <sub>G</sub> /dt≥1 A/μs	
I <sub>H</sub>	Holding current, max	mA	300	T <sub>j</sub> =25 °C; V <sub>D</sub> =12 V; Gate open	
<b>BLOCKING</b>					
I <sub>DRM</sub> , I <sub>RRM</sub>	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	T <sub>j</sub> =T <sub>j</sub> max; V <sub>D</sub> =V <sub>DRM</sub> ; V <sub>R</sub> =V <sub>RRM</sub>	
(dv <sub>D</sub> /dt) <sub>crit</sub>	Critical rate of rise of off-state voltage <sup>1)</sup> , min	V/μs	1000	T <sub>j</sub> =T <sub>j</sub> max; V <sub>D</sub> =0.67·V <sub>DRM</sub> ; Gate open	
<b>TRIGGERING</b>					
V <sub>GT</sub>	Gate trigger direct voltage, max	V	5.00 3.00 2.00	T <sub>j</sub> = T <sub>j</sub> min T <sub>j</sub> =25 °C T <sub>j</sub> = T <sub>j</sub> max	V <sub>D</sub> =12 V; I <sub>D</sub> =3 A; Direct gate current
I <sub>GT</sub>	Gate trigger direct current, max	mA	500 300 200	T <sub>j</sub> = T <sub>j</sub> min T <sub>j</sub> = 25 °C T <sub>j</sub> = T <sub>j</sub> max	
V <sub>GD</sub>	Gate non-trigger direct voltage, min	V	0.35	T <sub>j</sub> =T <sub>j</sub> max; V <sub>D</sub> =0.67·V <sub>DRM</sub> ;	
I <sub>GD</sub>	Gate non-trigger direct current, min	mA	15.00	Direct gate current	
<b>SWITCHING</b>					
t <sub>gd</sub>	Delay time	μs	3.50	T <sub>j</sub> =25 °C; V <sub>D</sub> =0.4·V <sub>DRM</sub> ; I <sub>TM</sub> =2000 A; Gate pulse: I <sub>G</sub> =2 A; t <sub>GP</sub> =50 μs; dI <sub>G</sub> /dt≥1 A/μs	
t <sub>q</sub>	Turn-off time <sup>2)</sup> , max	μs	800	dv <sub>D</sub> /dt=50 V/μs; T <sub>j</sub> =T <sub>j</sub> max; I <sub>TM</sub> =2000 A; di <sub>R</sub> /dt=-10 A/μs; V <sub>R</sub> =100 V; V <sub>D</sub> =0.67 V <sub>DRM</sub> ;	
Q <sub>rr</sub>	Total recovered charge, max	μC	9000	T <sub>j</sub> =T <sub>j</sub> max; I <sub>TM</sub> =2000 A;	
t <sub>rr</sub>	Reverse recovery time, typ	μs	90	di <sub>R</sub> /dt=-5 A/μs;	
I <sub>rrM</sub>	Peak reverse recovery current, max	A	200	V <sub>R</sub> =100 V	

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### **Thermal**

$R_{thjc}$	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0050	Direct current	Double side cooled
$R_{thjc-A}$			0.0110		Anode side cooled
$R_{thjc-K}$			0.0090		Cathode side cooled
$R_{thck}$	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0010	Direct current	

### **Mechanical**

w	Weight, typ	g	2200	
$D_s$	Surface creepage distance	mm (inch)	44.60 (1.756)	
$D_a$	Air strike distance	mm (inch)	15.70 (0.618)	

### **PART NUMBERING GUIDE**

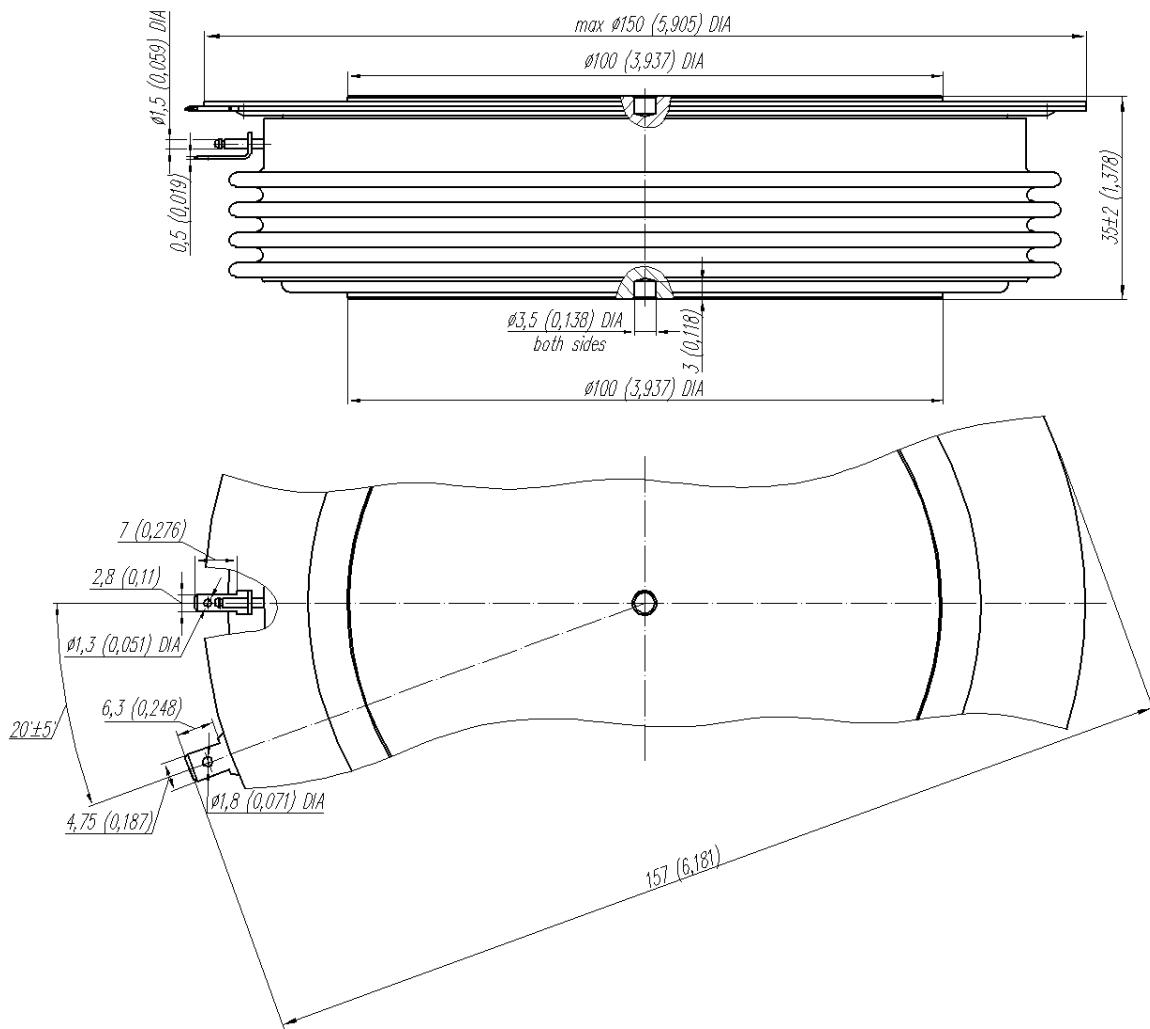
DT	99	3200	44
1	2	3	4
1. DT - Phase Control Disc Thyristor			
2. Element Diameter			
3. Mean on-state current, A			
4. Voltage code			

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### **OVERALL DIMENSIONS**

**Package type: T.G6**



All dimensions in millimeters (inches)